

2SK1838(L), 2SK1838(S)

Silicon N Channel MOS FET

REJ03G0980-0300 Rev.3.00 Nov 21, 2005

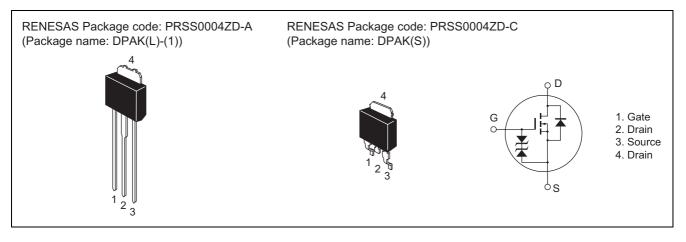
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator, DC-DC converter

Outline





Absolute Maximum Ratings

			$(Ta = 25^{\circ}C)$
Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	250	V
Gate to source voltage	V _{GSS}	±30	V
Drain current	ID	1	A
Drain peak current	I _{D(pulse)} *1	2	A
Body to drain diode reverse drain current	I _{DR}	1	A
Channel dissipation	Pch ^{*2}	10	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1 %

2. Value at $Tc = 25^{\circ}C$

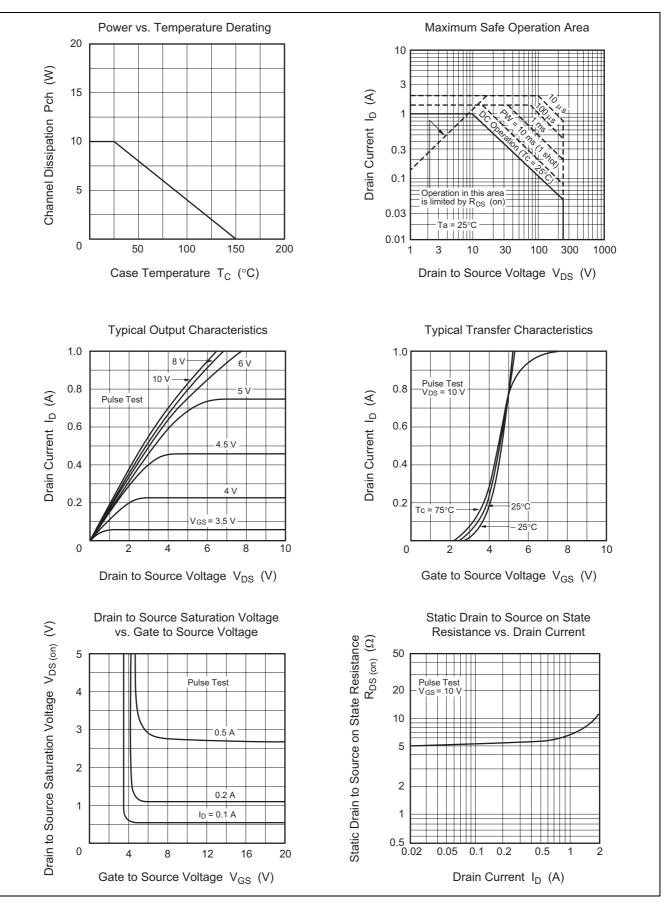
Electrical Characteristics

						(Ta = 25°C)
ltem	Symbol	Min	Тур	Мах	Unit	Test conditions
Drain to source breakdown voltage	V _{(BR)DSS}	250			V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V _{(BR)GSS}	±30	—	—	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	—	±10	μΑ	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	—	50	μΑ	$V_{DS} = 200 V, V_{GS} = 0$
Gate to source cutoff voltage	V _{GS(off)}	2.0	—	3.0	V	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA}$
Forward transfer admittance	y _{fs}	0.3	0.5	—	S	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 0.5 \text{ A}^{*3}$
Static drain to source on state resistance	R _{DS(on)}	—	5.5	8.0	Ω	$I_D = 0.5 \text{ A}, \text{ V}_{GS} = 10 \text{ V} *^3$
Input capacitance	Ciss	_	60	—	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$ f = 1 MHz
Output capacitance	Coss	_	30	—	pF	
Reverse transfer capacitance	Crss	_	5	—	pF	
Turn-on delay time	t _{d(on)}	_	5	—	ns	$V_{GS} = 10 \text{ V}, I_D = 0.5 \text{ A},$
Rise time	tr	_	6	—	ns	R _L = 60 Ω
Turn-off delay time	t _{d(off)}	_	10	—	ns	
Fall time	t _f	_	4.5	—	ns	
Body to drain diode forward voltage	V_{DF}		0.96	_	V	$I_{F} = 1 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}	—	160	—	ns	$I_F = 1 \text{ A}, V_{GS} = 0,$ $di_F/dt = 100 \text{ A}/\mu \text{s}$

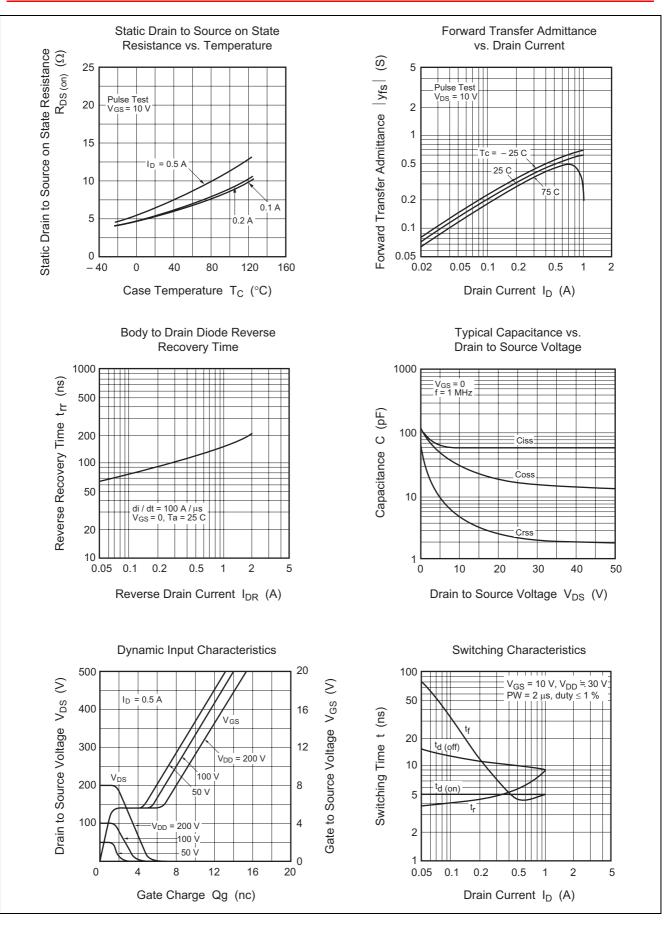
Note: 3. Pulse test



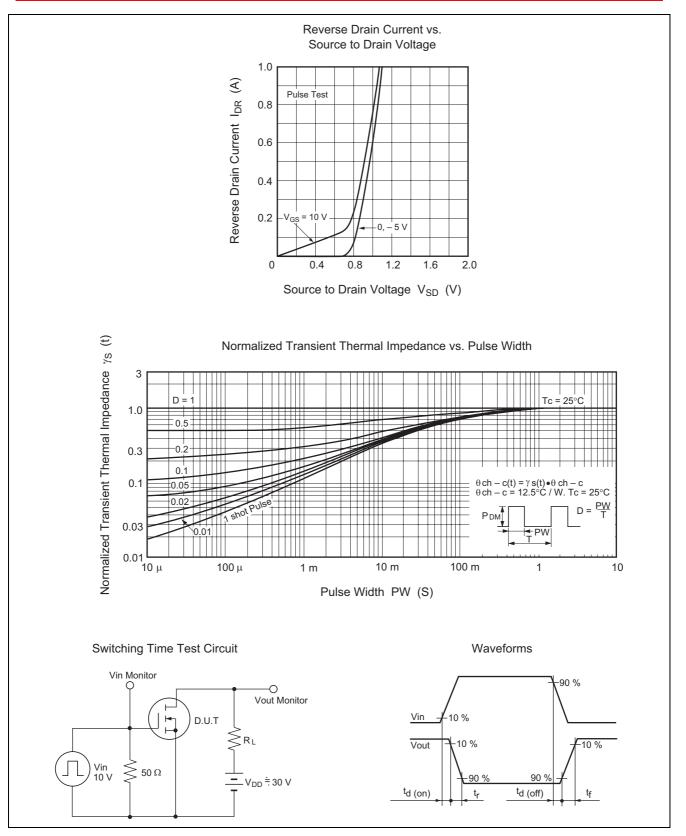
Main Characteristics



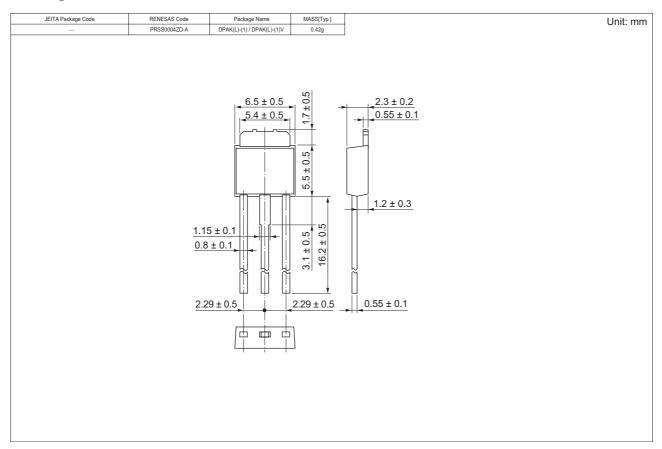


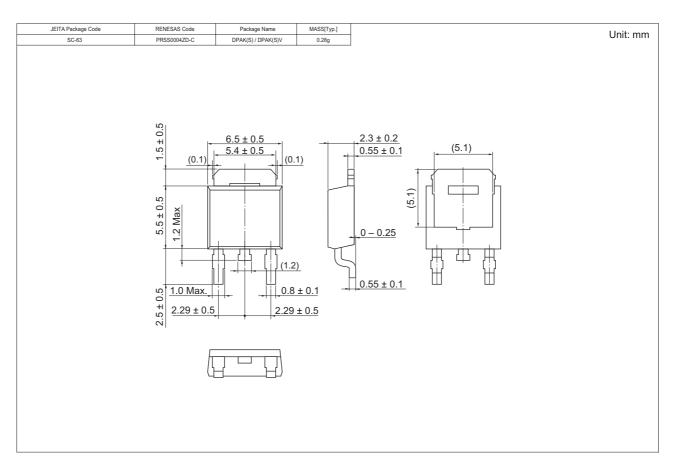






Package Dimensions







Ordering Information

Part Name	Quantity	Shipping Container
2SK1838L-E	3200 pcs	Box (Sack)
2SK1838STL-E	3000 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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